

PostDip SN 260

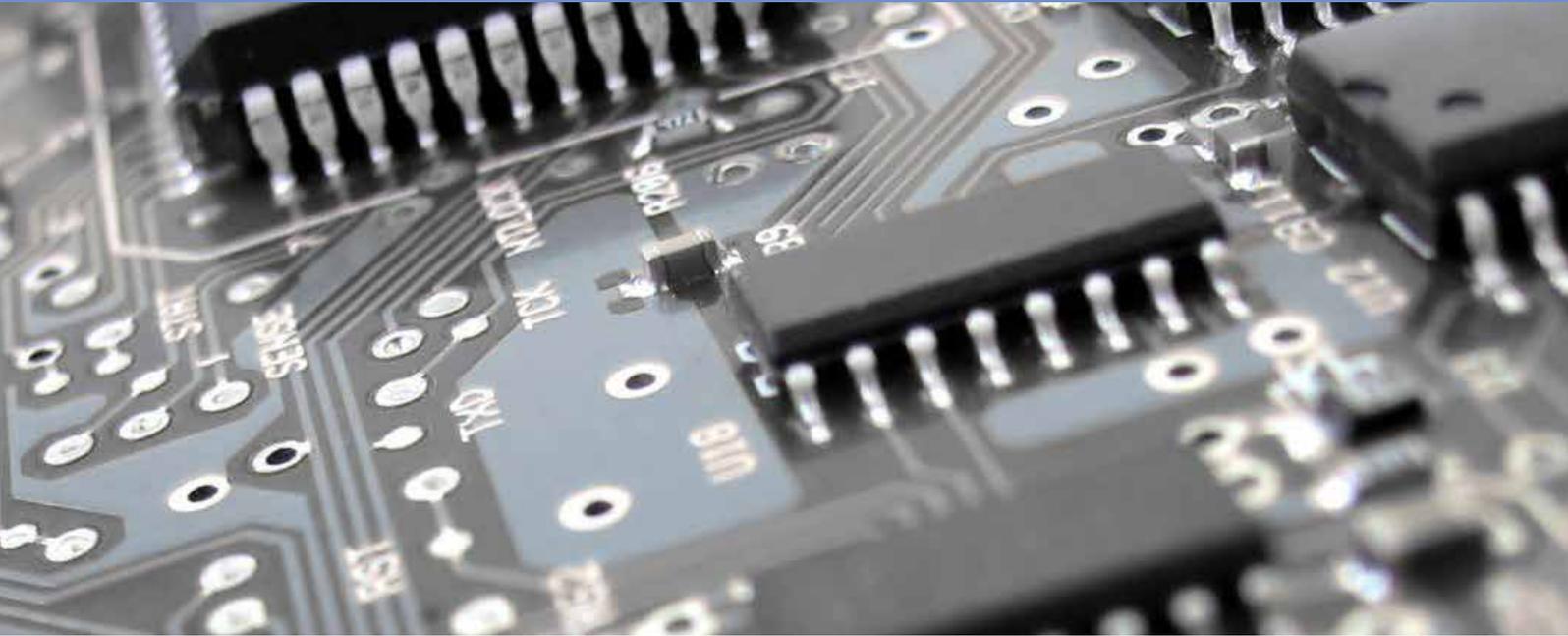
Tin posttreatment



Electronics

Functional electronic coatings

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Excellent solderability for connectors and ICs

Anti-tarnishing and solderability

Tin plated surfaces of connectors, leadframes and ICs are prone to tarnishing and loss of solderability especially if exposed to either heat or humidity. PostDip SN 260 has been developed to exactly tackle this well-known performance degradation.

The anti-tarnish preserves a perfect solderability even after multiple reflow cycles at 260 °C or exposure to humidity. PostDip SN 260 effectively inhibits growth of oxide layers on the tin surface through conversion into a phosphorized surface layer.

Properties

- Perfect solderability after multiple reflow cycles at $T > 260\text{ °C}$
- Preserves solderability even after steam aging e.g. at 85 °C/ 85% rel. humidity
- Simple application through dip tank technology
- High speed application
- High volume manufacturing proven

PostDip SN 260 – Effective anti-tarnish for tin deposits

Effective anti-tarnishing during heat exposure

Connectors and ICs often undergo multiple reflow cycles. Their tin plated parts are exposed to temperatures beyond 260 °C for lead free soldering processes. This heat exposure leads to significant tarnishing and a reduced solderability of the surfaces.

PostDip SN 260 offers a perfect anti-tarnish function and solderability as depicted in fig 1. Untreated connectors tarnish significantly at 260 resp 285 °C and will fail the solderability test (e.g. wetting balance test), whereas PostDip SN 260 treated parts maintain their original colour and will be solderable.

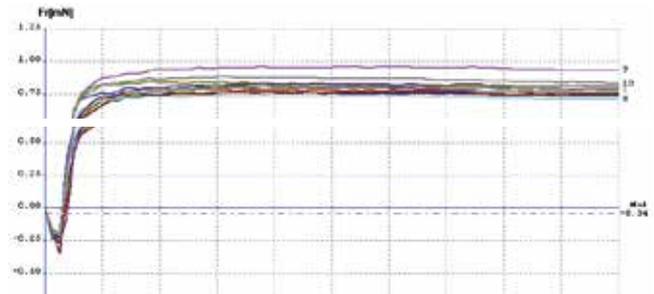


Figure 1: Connector pins treated with and without PostDip SN 260 after exposure to 260 and 285 °C

Perfect solderability even after humidity exposure

Exposure to humidity e.g. 24 h at 85 °C / 85% rel. RH is a standard test for connectors and ICs. Parts need to withstand this treatment without loss of solderability as tested by wetting

balance tests. Figure 2 shows an example of the untreated tin plated connector pins while figure 3 shows the PostDip SN 260 treated connectors after exposure to humidity.

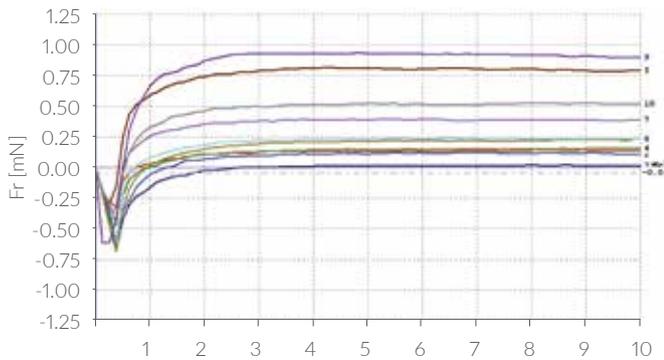


Figure 2: Untreated connectors after 24 h at 85 °C / 85% RH

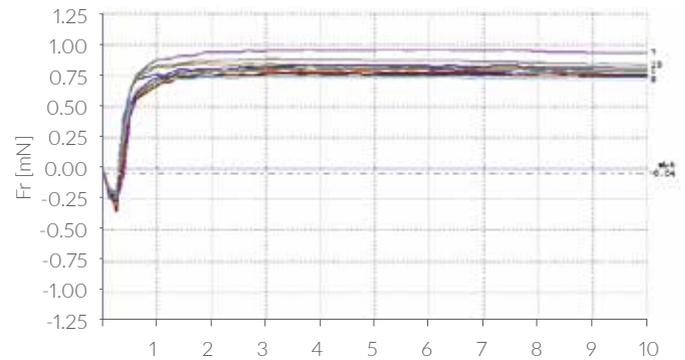


Figure 3: PostDip SN 260 treated connectors after 24 h at 85 °C / 85% RH

